

Abstract

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A circuit unit having
~~The invention relates to~~ a circuit unit comprising an insulating substrate (1) on which a conductive, flat coil (3) is located. The coil (3) can consist of a plurality of coil layers (9, 17) separated by insulating layers (11). To interconnect the individual coil layers ^{Section} (9, 17) into a coil, at least one opening (13) is provided in each of the insulating layers (11). The connection between the ^{first} coil ends (15, 19) of the coil (3) and an integrated circuit (7) or a module (23) containing the integrated circuit (7) can be formed solely by the coil ends (15, 19) and the connection points (27) of the integrated circuit (7) or the contacts (25) of the module (23) touching. The individual turns of the coil (3) can be disposed and dimensioned so as to permit embossing of the circuit unit without restriction within an area (37, 38) conforming with the standard.